

January 9, 2019

**VIEWPOINT 2019: Stéphane Tremblay, Site Business Development Manager, IBM Assembly & Test Services**

All through 2018, we have asserted our assembly and test proposition in several key areas providing solutions for high current and high thermal dissipation applications in computing electronics market and developing specialized areas with attractive know-how in RF, Antennas, SiP and advanced opto electronic packaging for communication and wireless markets.



Stéphane  
Tremblay, Site  
Business  
Development  
Manager, IBM  
Assembly & Test  
Services

Beyond our technical orientation, our experienced engineering team takes pride in using its design, assembly and test expertise to provide tailor-made solutions for our client's needs and bring forth designs, prototypes and manufacturing ramp ups that are key to our client's success.

Several fruitful collaborations have been enacted in the past months and we already have received feedback that it provides high value to the customers that have chosen us as their development and manufacturing OSAT solution. Clients also see value in our supply chain management proposition. Clearly beyond the customer-supplier relationship, we value true partnerships for mutual growth.

We have an exciting 2019 roadmap, some of the highlights include deploying high density interconnect laminates, pursuing integration and optimisation of SiP packages and also deploying technical milestones to prepare for dense optical integration which is highly anticipated by several key players of the communications market in the years ahead.

**Stéphane Tremblay, Site Business Development Manager  
IBM Assembly & Test Services**